



# TEST REPORT SUMMARY

(Short Report)

**CLIENT:** IPC Validation Services  
3000 Lakeside Drive Suite 105N Bannockburn, IL 60015  
Attention: Mr. Randy Cherry  
Phone: 1-847-597-2806

**REFERENCE:** IPC-4101E-WAM1/134, IPC-TM-650 2.3.1.1, 2.3.4.2A, 2.4.4B,  
2.4.8C, 2.4.8.3A, 2.4.13.1, 2.4.24C, 2.4.24.1, 2.4.24.4, 2.4.24.6,  
2.4.25D, 2.4.39, 2.5.1B, 2.5.5.9, 2.5.6B, 2.5.6.2A, 2.5.17.1A,  
2.6.2.1A, 2.6.16, UL94, Customer Technical Requirements

**TEST ITEM:** Peel Strength, Volume Resistivity, Surface Resistivity, Moisture  
Absorption, Dielectric Breakdown, Permittivity and Loss Tangent,  
Flexural Strength, Arc Resistance, Thermal Stress, Electric Strength,  
Vertical Burning Test, Glass Transition Temperature, Decomposition  
Temperature, Z-Axis CTE (TMA), Time to Delamination, Glass  
Transition Temperature (DMA), Dimensional Stability, Solderability,  
Chemical Resistance, Metal Surface Cleanability, Pressure Cooker  
Test

**SAMPLE:** CCL

**TEST MATERIAL:** TU-883

**SPECIFICATION:** IPC-4101E-WAM1/134

**TEST RESULTS:** The specimens were tested by the indicated test methods within this  
report. The actual detailed test results are enclosed.

**DATE OF REPORT:** 17 August 2022

**REPORT No.:** 34530E



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## SUMMARIZED TEST RESULTS:

<u>Test Item</u>	<u>Thin</u>	<u>Thick</u>
Peel Strength	Pass	Pass
Volume Resistivity	Pass	Pass
Surface Resistivity	Pass	Pass
Moisture Absorption	--	Pass
Dielectric Breakdown	--	Pass
Permittivity at 1 MHz, 1 GHz, 10 GHz, 20 GHz	Pass	Pass
Loss Tangent at 1 MHz, 1 GHz, 10 GHz, 20 GHz	Pass	Pass
Flexural Strength	--	Pass
Arc Resistance	Pass	Pass
Thermal Stress	Pass	Pass
Electric Strength	Pass	--
Vertical Burning	Pass	Pass
Glass Transition Temperature	--	Pass
Decomposition Temperature	--	Pass
Z-Axis CTE (TMA)	--	Pass
Time to Delamination	--	Pass
Glass Transition Temperature (DMA)	--	Pass
Dimensional Stability	Pass	Pass
Solderability	Pass	Pass
Chemical Resistance	Report Only	Report Only
Metal Surfaces Cleanability	--	Report Only
Pressure Cooker Test	--	Report Only



## Peel Strength

### REFERENCE

IPC-4101E-WAM1 Specification for Base Materials for Rigid and Multilayer Printed Boards  
 IPC-TM-650 Method 2.4.8C Peel Strength of Matallic Clad Laminates  
 IPC-TM-650 Method 2.4.8.3A Peel Strength of Matallic Clad Laminates at Elevated Customer Technical Requirements

### RESULTS

**Table 1 Peel Strength After Thermal Stress Thin**

Sample Designation	CCL		Sample Identification	TU-883
Test Date	2022-08-14		Ambient	25°C, 49%RH
Sample No.	Peel Strength (N/mm)			
	Top Crosswise	Top Lengthwise	Bottom Crosswise	Bottom Lengthwise
34530-101-1-1	0.98			
34530-101-1-2	0.98			
34530-101-1-3		1.05		
34530-101-1-4		1.06		
34530-101-1-5			0.91	
34530-101-1-6			0.93	
34530-101-1-7				0.94
34530-101-1-8				0.95
Average	0.98	1.05	0.92	0.94
Requirement	$\geq 0.70$			



Table 2 Peel Strength After Thermal Stress Thick

Sample Designation	CCL		Sample Identification	TU-883
Test Date	2022-08-14		Ambient	25°C, 49%RH
Sample No.	Peel Strength (N/mm)			
	Top Crosswise	Top Lengthwise	Bottom Crosswise	Bottom Lengthwise
34530-103-1-1	1.12			
34530-103-1-2	1.14			
34530-103-1-3		1.13		
34530-103-1-4		1.13		
34530-103-1-5			1.10	
34530-103-1-6			1.10	
34530-103-1-7				1.13
34530-103-1-8				1.13
Average	1.13	1.13	1.10	1.13
Requirement	$\geq 0.70$			



Table 3 Peel Strength At Elevated Temperature Thin

Sample Designation	CCL		Sample Identification	TU-883
Test Date	2022-08-15		Ambient	25°C, 49%RH
Sample No.	Peel Strength (N/mm)			
	Top Crosswise	Top Lengthwise	Bottom Crosswise	Bottom Lengthwise
34530-101-2-1	0.79			
34530-101-2-2	0.83			
34530-101-2-3		0.83		
34530-101-2-4		0.84		
34530-101-2-5			0.71	
34530-101-2-6			0.73	
34530-101-2-7				0.73
34530-101-2-8				0.74
Average	0.81	0.84	0.72	0.73
Requirement	$\geq 0.70$			



Table 4 Peel Strength At Elevated Temperature Thick

Sample Designation	CCL		Sample Identification	TU-883
Test Date	2022-08-15		Ambient	25°C, 49%RH
Sample No.	Peel Strength (N/mm)			
	Top Crosswise	Top Lengthwise	Bottom Crosswise	Bottom Lengthwise
34530-103-2-1	0.87			
34530-103-2-2	0.89			
34530-103-2-3		0.86		
34530-103-2-4		0.86		
34530-103-2-5			0.85	
34530-103-2-6			0.85	
34530-103-2-7				0.85
34530-103-2-8				0.86
Average	0.88	0.86	0.85	0.85
Requirement	$\geq 0.70$			





Table 5 Peel Strength After Process Solution Thin

Sample Designation	CCL		Sample Identification	TU-883
Test Date	2022-08-14		Ambient	25°C, 49%RH
Sample No.	Peel Strength (N/mm)			
	Top Crosswise	Top Lengthwise	Bottom Crosswise	Bottom Lengthwise
34530-100-1-1	1.01			
34530-100-1-2	0.98			
34530-100-1-3		0.99		
34530-100-1-4		0.95		
34530-100-1-5			1.12	
34530-100-1-6			1.11	
34530-100-1-7				1.11
34530-100-1-8				1.14
Average	1.00	0.97	1.12	1.12
Requirement	$\geq 0.70$			



Table 6 Peel Strength After Process Solution Thick

Sample Designation	CCL		Sample Identification	TU-883
Test Date	2022-08-14		Ambient	25°C, 49%RH
Sample No.	Peel Strength (N/mm)			
	Top Crosswise	Top Lengthwise	Bottom Crosswise	Bottom Lengthwise
34530-102-1-1	1.11			
34530-102-1-2	1.12			
34530-102-1-3		1.18		
34530-102-1-4		1.14		
34530-102-1-5			1.20	
34530-102-1-6			1.13	
34530-102-1-7				1.12
34530-102-1-8				1.15
Average	1.11	1.16	1.17	1.14
Requirement	≥0.70			





Table 7 Peel Strength Low Profile Copper Foil Thin

Sample Designation	/			Sample Identification	/
Test Date	/			Ambient	/
Sample No.	Peel Strength (N/mm)				
	Top Crosswise	Top Lengthwise	Bottom Crosswise	Bottom Lengthwise	
No Requirement					


**Table 8 Peel Strength Low Profile Copper Foil Thick**

Sample Designation	/			Sample Identification	/
Test Date	/			Ambient	/
Sample No.	Peel Strength (N/mm)				
	Top Crosswise	Top Lengthwise	Bottom Crosswise	Bottom Lengthwise	
No Requirement					



## Volume and Surface Resistivity

### REFERENCE

IPC-4101E-WAM1 Specification for Base Materials for Rigid and Multilayer Printed Boards

IPC-TM-650 2.5.17.1A Volume and Surface Resistivity of Dielectric Materials  
Customer Technical Requirements

### RESULTS

**Table 9 Volume and Surface resistivity Humidity Conditioning Thin**

Sample Designation	CCL		Sample Identification	TU-883	
Test Date	2022-07-14~2022-07-18		Ambient	25 °C, 52% RH	
Sample No.	Average Thickness T	Surface Resistance R'	Surface Resistivity $r'=R'P/D_4$	Volume Resistance R	Volume Resistivity $r=RA/T$
	(cm)	(MΩ)	(MΩ)	(MΩ)	(MΩ-cm)
34530-3-1	0.0117	8.0E+05	2.6E+08	5.8E+05	2.6E+08
34530-3-2	0.0114	7.0E+05	2.3E+08	6.0E+05	2.7E+08
34530-3-3	0.0115	7.5E+05	2.4E+08	6.0E+05	2.7E+08
<b>Average</b>		/	2.4E+08	/	2.7E+08
<b>Requirement</b>		/	$\geq 10^5$	/	$\geq 10^6$



Table 10 Volume and Surface Resistivity at Elevated Temperature Humidity Thin

Sample Designation	CCL		Sample Identification	TU-883	
Test Date	2022-07-19~2022-07-20		Ambient	25 °C, 53% RH	
Sample No.	Average Thickness T	Surface Resistance R'	Surface Resistivity $r'=R'P/D_4$	Volume Resistance R	Volume Resistivity $r=RA/T$
	(cm)	(MΩ)	(MΩ)	(MΩ)	(MΩ·cm)
34530-4-1	0.0117	1.6E+05	5.2E+07	1.2E+05	5.3E+07
34530-4-2	0.0118	1.6E+05	5.2E+07	1.4E+05	6.1E+07
34530-4-3	0.0116	1.4E+05	4.5E+07	1.2E+05	5.3E+07
Average		/	4.9E+07	/	5.6E+07
Requirement		/	$\geq 10^5$	/	$\geq 10^6$

Table 11 Volume and Surface Resistivity Humidity Conditioning Thick

Sample Designation	CCL		Sample Identification	TU-883	
Test Date	2022-07-14~2022-07-21		Ambient	23 °C, 53% RH	
Sample No.	Average Thickness T	Surface Resistance R'	Surface Resistivity $r'=R'P/D_4$	Volume Resistance R	Volume Resistivity $r=RA/T$
	(cm)	(MΩ)	(MΩ)	(MΩ)	(MΩ·cm)
34530-23-1	0.0616	8.0E+05	2.3E+07	7.5E+05	3.1E+08
34530-23-2	0.0617	1.0E+06	2.8E+07	8.0E+05	3.3E+08
34530-23-3	0.0615	9.0E+05	2.5E+07	8.0E+05	3.3E+08
Average		/	2.5E+07	/	3.3E+08
Requirement		/	$\geq 10^5$	/	$\geq 10^6$

**Table 12 Volume and Surface Resistivity at Elevated Temperature Humidity Thick**

Sample Designation	CCL		Sample Identification	TU-883	
Test Date	2022-07-14~2022-07-15		Ambient	24 °C, 48% RH	
Sample No.	Average Thickness T	Surface Resistance R'	Surface Resistivity $r'=R'P/D_4$	Volume Resistance R	Volume Resistivity $r=RA/T$
	(cm)	(MΩ)	(MΩ)	(MΩ)	(MΩ·cm)
34530-24-1	0.0617	1.6E+05	4.5E+06	1.4E+05	5.8E+07
34530-24-2	0.0614	1.8E+05	5.1E+06	1.2E+05	5.0E+07
34530-24-3	0.0615	1.6E+05	4.5E+06	1.2E+05	5.0E+07
Average		/	4.7E+06	/	5.3E+07
Requirement		/	$\geq 10^5$	/	$\geq 10^6$



## Moisture Absorption

### REFERENCE

IPC-4101E-WAM1 Specification for Base Materials for Rigid and Multilayer Printed Boards

IPC-TM-650 Method 2.6.2.1A Water Absorption, Metal Clad Plastic Laminates  
Customer Technical Requirements

### RESULTS

**Table 13 Moisture Absorption**

Sample Designation	CCL		Sample Identification	TU-883
Test Date	2022-07-07~2022-07-14		Ambient	28 °C, (50~54)% RH
Sample No.	mass(g)		increasing weight percent of mass(%)	
	m <sub>1</sub>	m <sub>2</sub>		
34530-26-4	2.7270	2.7308	0.14	
34530-26-5	2.7325	2.7361	0.13	
34530-26-6	2.7090	2.7131	0.15	
Average			0.14	
Requirement			≤0.2	



## Dielectric Breakdown

### REFERENCE

IPC-4101E-WAM1 Specification for Base Materials for Rigid and Multilayer Printed Boards

IPC-TM-650 Method 2.5.6B Dielectric Breakdown of Rigid Printed Wiring Material  
Customer Technical Requirements

### RESULTS

**Table 14 Dielectric Breakdown**

Sample Designation		CCL	Sample Identification	TU-883
Test Date		2022-07-10~2022-07-12	Ambient	25 °C, 50% RH
Sample No.		Thickness (mm)	Voltage (kV)	Minimum Voltage (kV)
34530-27-1	Machine direction	0.614	43.2+N.B	43+N.B
34530-27-2		0.613	43.2+N.B	
34530-27-3	Transverse direction	0.614	43.4+N.B	
34530-27-4		0.612	43.1+N.B	
Requirement				≥40





## Permittivity and Loss Tangent

### REFERENCE

IPC-4101E-WAM1 Specification for Base Materials for Rigid and Multilayer Printed Boards  
IPC-TM-650 Method 2.5.5.9 Permittivity and Loss Tangent, Parallel Plate, 1MHz to 1.5GHz  
Customer Technical Requirements

### RESULTS



Table 15 Permittivity and Loss Tangent

Sample Designation	CCL		Sample Identification	TU-883
Test Date	2022-07-07~2022-07-15		Ambient	(24~25) °C, (48~49)% RH
Sample No.	Test Frequency	Sample Thickness (mm)	Permittivity	Loss Tangent
34530-6-1	1 MHz	0.110	2.9	0.003
34530-6-2		0.109	2.9	0.003
34530-6-3		0.111	2.9	0.003
<b>Average</b>		0.110	2.9	0.003
<b>Requirement</b>			≤4.3	≤0.006
34530-26-7	1 MHz	0.608	3.7	0.002
34530-26-8		0.608	3.7	0.002
34530-26-9		0.609	3.7	0.002
<b>Average</b>		0.608	3.7	0.002
<b>Requirement</b>			≤4.3	≤0.006
34530-6-4	1 GHz	0.123	3.4	0.001
34530-6-5		0.125	3.3	0.001
34530-6-6		0.123	3.4	0.001
<b>Average</b>		0.124	3.4	0.001
<b>Requirement</b>			≤4.3	≤0.006
34530-26-10	1 GHz	0.624	3.8	0.003
34530-26-11		0.620	3.8	0.003
34530-26-12		0.620	3.8	0.003
<b>Average</b>		0.621	3.8	0.003
<b>Requirement</b>			≤4.3	≤0.006
34530-17-1	10 GHz	0.114	3.6	0.004
34530-17-2		0.150	3.6	0.005
34530-17-3		0.150	3.5	0.005
<b>Average</b>		0.138	3.6	0.004
<b>Requirement</b>			≤4.2	≤0.006
34530-40-1	10 GHz	0.660	3.8	0.005
34530-40-2		0.710	3.8	0.005
34530-40-3		1.066	3.8	0.005
<b>Average</b>		0.812	3.8	0.005
<b>Requirement</b>			≤4.2	≤0.006
34530-17-4	20 GHz	0.114	3.6	0.005
34530-17-5		0.150	3.6	0.005
34530-17-6		0.150	3.7	0.005
<b>Average</b>		0.138	3.6	0.005
<b>Requirement</b>			≤4.2	≤0.006
34530-40-4	20 GHz	0.660	3.8	0.005
34530-40-5		0.710	3.8	0.005
34530-40-6		1.066	3.8	0.005
<b>Average</b>		0.812	3.8	0.005
<b>Requirement</b>			≤4.2	≤0.006



## Flexural Strength

### REFERENCE

IPC-4101E-WAM1 Specification for Base Materials for Rigid and Multilayer Printed Boards

IPC-TM-650 2.4.4B Flexural Strength of Laminates (at Ambient Temperature)

Customer Technical Requirement

### RESULTS

**Table 16 Flexural Strength Test**

Sample Designation	CCL		Sample Identification		TU-883		
Test Date	2022-07-18		Ambient		24°C, 49%RH		
Sample No.	Span	Load	Width	Thickness	Flexural Strength S	Average	Requirement
	L	P	b	d			
	(mm)	(N)	(mm)	(mm)			
34530-28-1 (Length Direction)	15.90	155.269	26.04	0.611	381	372	≥345
34530-28-2 (Length Direction)		148.628	25.70	0.616	363		
34530-28-3 (Cross Direction)		142.776	25.71	0.616	349	347	≥345
34530-28-4 (Cross Direction)		138.795	25.44	0.615	344		



## Arc Resistance

### REFERENCE

IPC-4101E-WAM1 Specification for Base Materials for Rigid and Multilayer Printed Boards

IPC-TM-650 Method 2.5.1B Arc Resistance of Printed Wiring Material  
Customer Technical Requirements

### RESULTS

**Table 17 Arc Resistance**

Sample Designation	CCL	Sample Identification	TU-883	
Test Date	2022-07-10~2022-07-12	Ambient	25 °C, 49% RH	
Sample No.	Thickness	Times	Average	Requirement
	(mm)	(s)	(s)	(s)
34530-7-1	0.117	181	181	≥60
34530-7-2	0.115	181		
34530-7-3	0.116	181		
34530-29-1	0.614	182	182	
34530-29-2	0.615	181		
34530-29-3	0.617	182		



## Thermal Stress

### REFERENCE

IPC-4101E-WAM1 Specification for Base Materials for Rigid and Multilayer Printed Boards

IPC-TM-650 Method 2.4.13.1 Thermal Stress of Laminates

Customer Technical Requirements

### RESULTS

Table 18 Thermal Stress

Sample Designation	CCL		Sample Identification	TU-883
Test Date	2022-07-12		Ambient	25 °C, 47%RH
Sample No.			Test result	
34530-8-1	Etched	Top	Thin	No evidence of blistering, delamination, wrinkling and cracking
34530-8-2				No evidence of blistering, delamination, wrinkling and cracking
34530-8-3				No evidence of blistering, delamination, wrinkling and cracking
34530-8-4		Bottom		No evidence of blistering, delamination, wrinkling and cracking
34530-8-5				No evidence of blistering, delamination, wrinkling and cracking
34530-8-6				No evidence of blistering, delamination, wrinkling and cracking
34530-30-1	Unetched	Top	Thick	No evidence of blistering, delamination, wrinkling and cracking
34530-30-2				No evidence of blistering, delamination, wrinkling and cracking
34530-30-3				No evidence of blistering, delamination, wrinkling and cracking
34530-30-4		Bottom		No evidence of blistering, delamination, wrinkling and cracking
34530-30-5				No evidence of blistering, delamination, wrinkling and cracking
34530-30-6				No evidence of blistering, delamination, wrinkling and cracking
34530-9-1	Unetched	Top	Thin	No evidence of blistering, delamination, wrinkling and cracking
34530-9-2				No evidence of blistering, delamination, wrinkling and cracking
34530-9-3				No evidence of blistering, delamination, wrinkling and cracking
34530-9-4		Bottom		No evidence of blistering, delamination, wrinkling and cracking
34530-9-5				No evidence of blistering, delamination, wrinkling and cracking
34530-9-6				No evidence of blistering, delamination, wrinkling and cracking
34530-31-1	Unetched	Top	Thick	No evidence of blistering, delamination, wrinkling and cracking
34530-31-2				No evidence of blistering, delamination, wrinkling and cracking
34530-31-3				No evidence of blistering, delamination, wrinkling and cracking
34530-31-4		Bottom		No evidence of blistering, delamination, wrinkling and cracking
34530-31-5				No evidence of blistering, delamination, wrinkling and cracking
34530-31-6				No evidence of blistering, delamination, wrinkling and cracking



## Electric Strength

### REFERENCE

IPC-4101E-WAM1 Specification for Base Materials for Rigid and Multilayer Printed Boards

IPC-TM-650 Method 2.5.6.2A Electric Strength of Printed Wiring Material

Customer Technical Requirements

### RESULTS

**Table 19 Electric Strength**

Sample Designation	CCL	Sample Identification	TU-883
Test Date	2022-07-10~2022-07-12	Ambient	25 °C, 50% RH
Sample No.	Average Thickness (mm)	Voltage (kV)	Electric Strength (kV/mm)
34530-10-1	0.116	8.4	72.41
34530-10-2	0.117	8.7	74.36
34530-10-3	0.118	8.7	73.73
Average			74
Requirement			≥30





## Vertical Burning Test

### REFERENCE

IPC-4101E-WAM1 Specification for Base Materials for Rigid and Multilayer Printed Boards

UL94 STANDARD FOR SAFETY Tests for Flammability of Plastic Materials for Parts in Devices and Appliances Section 8 50W (20 mm) Vertical Burning Test; V-0, V-1, or V-2

Customer Technical Requirements

### RESULTS

**Table 20 Vertical Burning Test Thin**

Sample Designation		CCL		Sample Identification		TU-883			
Test Date		2022-07-14~2022-07-20		Ambient		25 °C, 51% RH			
Pre-conditioning	Sample No.	Sample Thk (mm)	Afterflames (s)		Afterglow (s)	Sum of after flames (s)	Sum of afterflame and afterglow (s)	Did samples burn to the clamp?	Did the cotton ignite?
			(t <sub>1</sub> )	(t <sub>2</sub> )					
<b>Condition A:</b>	34530-11-1	0.119	0	0	0	0	0	No	No
<b>48 Hours</b>	34530-11-2	0.117	0	0	0	0	0	No	No
<b>(23±2) °C</b>	34530-11-3	0.118	0	0	0	0	0	No	No
<b>(50±10)% RH</b>	34530-11-4	0.119	0	0	0	0	0	No	No
	34530-11-5	0.118	0	0	0	0	0	No	No
	<b>Avg:</b>	<b>0.118</b>	<b>Max: 0</b>			<b>Sum: 0</b>	<b>Max: 0</b>	<b>Pass</b>	<b>Pass</b>
<b>Condition B:</b>	34530-11-6	0.120	0	0	0	0	0	No	No
<b>24 Hours</b>	34530-11-7	0.119	0	0	0	0	0	No	No
<b>(125±2) °C</b>	34530-11-8	0.118	0	0	0	0	0	No	No
	34530-11-9	0.117	0	0	0	0	0	No	No
<b>Results</b>	34530-11-10	0.118	0	0	0	0	0	No	No
<b>V-0</b>	<b>Avg:</b>	<b>0.118</b>	<b>Max: 0</b>			<b>Sum: 0</b>	<b>Max: 0</b>	<b>Pass</b>	<b>Pass</b>
<b>Requirement</b>	V-0								





Table 21 Vertical Burning Test Thick

Sample Designation		CCL			Sample Identification		TU-883		
Test Date		2022-07-14~2022-07-20			Ambient		25 °C, 51% RH		
Pre-conditioning	Sample No.	Sample Thk (mm)	Afterflames (s)		Afterglow (s)	Sum of after flames (s)	Sum of afterflame and afterglow (s)	Did samples burn to the clamp?	Did the cotton ignite?
			(t <sub>1</sub> )	(t <sub>2</sub> )					
Condition A:	34530-32-1	0.617	8	0	0	8	0	No	No
48 Hours	34530-32-2	0.616	8	0	0	8	0	No	No
(23±2) °C	34530-32-3	0.615	7	0	0	7	0	No	No
(50±10)% RH	34530-32-4	0.614	6	0	0	6	0	No	No
	34530-32-5	0.615	8	0	0	8	0	No	No
	<b>Avg:</b>	<b>0.615</b>	<b>Max: 8</b>			<b>Sum: 37</b>	<b>Max: 0</b>	<b>Pass</b>	<b>Pass</b>
Condition B:	34530-32-6	0.617	7	0	0	7	0	No	No
24 Hours	34530-32-7	0.615	6	0	0	6	0	No	No
(125±2) °C	34530-32-8	0.618	8	0	0	8	0	No	No
	34530-32-9	0.617	6	0	0	6	0	No	No
Results	34530-32-10	0.616	7	0	0	7	0	No	No
V-0	<b>Avg:</b>	<b>0.617</b>	<b>Max: 8</b>			<b>Sum: 34</b>	<b>Max: 0</b>	<b>Pass</b>	<b>Pass</b>
Requirement	V-0								



## Glass Transition Temperature

### REFERENCE

IPC-4101E-WAM1 Specification for Base Materials for Rigid and Multilayer Printed Boards

IPC-TM-650 Method 2.4.25D Glass Transition Temperature and Cure Factor by DSC

Customer Technical Requirement

### RESULTS

**Table 22 Glass Transition Temperature**

<b>Sample Designation</b>	CCL	<b>Sample Identification</b>	TU-883
<b>Test Date</b>	2022-07-07~2022-07-12	<b>Ambient</b>	28 °C, 52% RH
<b>Sample Number</b>	34530-37-7		
<b>Element</b>	<b>Measurement (°C)</b>		<b>Requirement</b>
<b>Tg1</b>	/		/
<b>Tg2</b>	/		/
<b>Cure Factor <math>\Delta T_g</math></b>	/		/



## Decomposition Temperature

### REFERENCE

IPC-4101E-WAM1 Specification for Base Materials for Rigid and Multilayer Printed Boards

IPC-TM-650 method 2.4.24.6 Decomposition Temperature (Td) of Laminate Material Using TGA

Customer Technical Requirements

### RESULTS

**Table 23 Decomposition Temperature**

<b>Sample Designation</b>	CCL	<b>Sample Identification</b>	TU-883
<b>Test Date</b>	2022-07-07~2022-07-11	<b>Ambient</b>	28 °C, 56% RH
<b>Sample Number</b>	<b>Decomposition temperature (°C)</b>		
	<b>mass loss at 2%</b>	<b>mass loss at 5%</b>	
34530-26-3	427.75	444.57	
Requirement	/	≥400	



### Z-Axis CTE (TMA)

#### REFERENCE

IPC-4101E-WAM1 Specification for Base Materials for Rigid and Multilayer Printed Boards

IPC-TM-650 Method 2.4.24C Glass Transition Temperature and Z-Axis Thermal Expansion by TMA

Customer Technical Requirements

#### RESULTS

**Table 24 Z-Axis CTE (TMA)**

Sample Designation	CCL		Sample Identification	TU-883	
Test Date	2022-07-07~2022-07-11		Ambient	28 °C, 56% RH	
Sample Number	Z-CTE( $\mu\text{m}/\text{m}\cdot^{\circ}\text{C}$ )			PTE (%)	Tg( $^{\circ}\text{C}$ )
	(50~100) $^{\circ}\text{C}$	(200~250) $^{\circ}\text{C}$	(50~260) $^{\circ}\text{C}$	(50~260) $^{\circ}\text{C}$	
34530-26-1	49.05	183.9	101.1	2.12	197.27
34530-26-2	45.91	184.7	101.9	2.14	195.28
Requirement	$\leq 50$	$\leq 275$	/	$\leq 2.8$	$\geq 170$



## Time to Delamination

### REFERENCE

IPC-4101E-WAM1 Specification for Base Materials for Rigid and Multilayer Printed Boards

IPC-TM-650 Method 2.4.24.1 Time to Delamination (TMA Method)

Customer Technical Requirements

### RESULTS

**Table 25 Time to Delamination**

Sample Designation	CCL	Sample Identification	TU-883	
Test Date	2022-07-07~2022-07-14	Ambient	28 °C, (50~54)% RH	
Sample No.	Test Item	Time of Reversible Event (min)	Time of Delaminate (min)	Requirement (min)
34530-37-1	T260	/	>60	≥60
34530-37-2		/	>60	
34530-37-3	T288	/	>60	≥60
34530-37-4		/	>60	
34530-37-5	T300	/	>30	≥30
34530-37-6		/	>30	



## Glass Transition Temperature (DMA)

### REFERENCE

IPC-4101E-WAM1 Specification for Base Materials for Rigid and Multilayer Printed Boards

IPC-TM-650 Method 2.4.24.4 Glass Transition and Modulus of Materials Used in High Density Interconnection (HDI) and Microvias-DMA Method

Customer Technical Requirements

### RESULTS

**Table 26 Glass Transition Temperature(DMA)**

<b>Sample Designation</b>	CCL	<b>Sample Identification</b>	TU-883
<b>Test Date</b>	2022-07-14	<b>Ambient</b>	25 °C, 65% RH
<b>Sample No.</b>	<b>Tg (°C)</b>		
34530-39-1	231.14		
<b>Requirement</b>	≥170		



## Dimensional Stability

### REFERENCES

IPC-4101E-WAM1 Specification for Base Materials for Rigid and Multilayer Printed Boards  
 IPC-TM-650 Method 2.4.39A Dimensional Stability, Glass Reinforced Thin Laminates  
 Customer Technical Requirement

### RESULTS

**Table 27 Dimensional Stability Thin**

Sample Designation	CCL				Sample Identification	TU-883			
Test Date	2022-07-28~2022-08-01				Ambient	23°C, 49% RH			
Sample No.	After Bake Process (ppm)				After Thermal Stress Process (ppm)				
	MD		TD		MD		TD		
34530-39	-132	-52	-51	-35	-172	-52	-129	-106	
34530-40	-64	-60	-47	-28	-189	-217	-71	-110	
34530-41	-76	-76	-75	-51	-169	-165	-165	-244	
Requirement	-300~300								

**Table 28 Dimensional Stability Thick**

Sample Designation	CCL				Sample Identification	TU-883			
Test Date	2022-07-18~2022-07-20				Ambient	(23~25)°C, 49% RH			
Sample No.	After Bake Process (ppm)				After Thermal Stress Process (ppm)				
	MD		TD		MD		TD		
34530-33	-4	-32	-4	-47	-12	-100	-27	-126	
34530-34	36	-32	0	-47	-36	-145	-82	-130	
34530-35	12	-36	-98	-63	-80	-156	-122	-130	
Requirement	-300~300								





## Solderability

### REFERENCE

IPC-4101E-WAM1 Specification for Base Materials for Rigid and Multilayer Printed Boards

IPC J-STD-003C Solderability Tests for Printed Boards Section 4.2.1 Edge Dip Test  
Customer Technical Requirements

### RESULTS

**Table 29 Solderability**

Sample Designation	CCL	Sample Identification	TU-883
Test Date	2022-07-12	Ambient	25 °C, 49% RH
Sample No.		Test result	
34530-15-1	Thin	Sample surface exhibits good wetting	
34530-15-2		Sample surface exhibits good wetting	
34530-15-3		Sample surface exhibits good wetting	
34530-36-1	Thick	Sample surface exhibits good wetting	
34530-36-2		Sample surface exhibits good wetting	
34530-36-3		Sample surface exhibits good wetting	



## Chemical Resistance

### REFERENCE

IPC-4101E-WAM1 Specification for Base Materials for Rigid and Multilayer Printed Boards  
 IPC-TM-650 Method 2.3.4.2A Chemical Resistance of Laminates, Prepreg, and Coated Foil Products, by Solvent Exposure  
 Customer Technical Requirements

### RESULTS

**Table 30 Chemical Resistance**

Sample Designation	CCL			Sample Identification	TU-883	
Test Date	2022-07-07~2022-07-14			Ambient	28 °C, 54% RH	
Sample No.	Thickness (mm)	Weight (mg)		Increase Weight (mg)	Appearance Inspection	
		W <sub>1</sub>	W <sub>2</sub>	W <sub>2</sub> -W <sub>1</sub>	After Bake	After Immerse in the Solvent
34530-6-7	0.120	486.8	506.7	19.9	no any change	no any change
34530-6-8	0.120	481.2	499.8	18.6	no any change	no any change
34530-6-9	0.120	486.1	505.9	19.8	no any change	no any change
Average				19.4	/	
34530-26-13	0.622	2759.3	2779.4	20.1	no any change	no any change
34530-26-14	0.619	2730.2	2752.2	22.0	no any change	no any change
34530-26-15	0.619	2747.3	2771.2	23.9	no any change	no any change
Average				22.0	/	



## Metal Surface Cleanability

### REFERENCE

IPC-4101E-WAM1 Specification for Base Materials for Rigid and Multilayer Printed Boards  
 IPC-TM-650 Method 2.3.1.1 Chemical Cleaning of Metal-Clad Laminate  
 Customer Technical Requirements

### RESULTS

**Table31 Metal Surface Cleanability**

Sample Designation	CCL	Sample Identification	TU-883
Test Date	2022-07-07~2022-07-15	Ambient	28 °C, 50% RH
Sample Number	Test Result		
34530-37-8	The metal cladding on the test specimen shall be cleaned to a uniform matte finish. Deionized or distilled water poured on the metal surface does not bead or form puddles.		
34530-37-9	The metal cladding on the test specimen shall be cleaned to a uniform matte finish. Deionized or distilled water poured on the metal surface does not bead or form puddles.		
34530-37-10	The metal cladding on the test specimen shall be cleaned to a uniform matte finish. Deionized or distilled water poured on the metal surface does not bead or form puddles.		
Requirements	The metal cladding on the test specimen shall be cleaned to a uniform matte finish. Deionized or distilled water poured on the metal surface does not bead or form puddles.		



## Pressure Cooker Test

### REFERENCE

IPC-4101E-WAM1 Specification for Base Materials for Rigid and Multilayer Printed Boards

IPC-TM 650 2.6.16 Pressure Vessel Method for Glass Epoxy Laminate Integrity  
Customer Technical Requirements

### RESULTS

#### Table 32 Pressure Cooker Test

Sample Designation	CCL	Sample Identification	TU-883
Test Date	2022-07-14	Ambient	25 °C, 50% RH
Sample No.	Test result		
34530-38-1	Grade 5: The sample have no measles, blisters, or surface erosion.		
34530-38-2	Grade 5: The sample have no measles, blisters, or surface erosion.		
34530-38-3	Grade 5: The sample have no measles, blisters, or surface erosion.		
34530-38-4	Grade 5: The sample have no measles, blisters, or surface erosion.		
34530-38-5	Grade 5: The sample have no measles, blisters, or surface erosion.		

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